

## 101364C

## RD60-2.8-16U-60 MHz Dispersive Delay Line 2.8 MHz Bandwidth

## **Specifications**

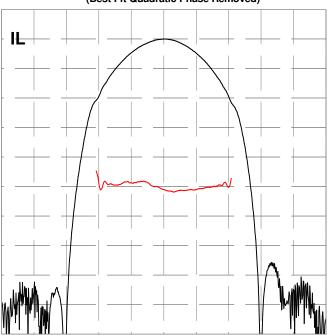
| Parameter                         | Symbol         | Min  | Typical | Max   | Unit   |
|-----------------------------------|----------------|------|---------|-------|--------|
| Center Frequency                  | F <sub>0</sub> |      | 60      |       | MHz    |
| Bandwidth                         | В              |      | 2.8     |       | MHz    |
| Dispersion                        | Т              |      | 16      |       | µsec   |
| Delay                             | T <sub>0</sub> | 29.1 | 29.153  | 29.2  | µsec   |
| Insertion Loss                    | IL             |      | 28      | 28.5  | dB     |
| Slope                             | S <sub>0</sub> | 17.8 | 17.9    | 18    | µs/MHz |
| Pulse Width at -3 dB              |                |      | 0.475   | 0.492 | µsec   |
| Sidelobes for $ t - T_0  < T$     |                |      | -46.4   | -42   | dB     |
| Time Spurious for $ t - T_0  > T$ |                |      | -81     | -80   | dB     |
| Substrate Material                | STQ            |      |         |       |        |

#### **Notes**

- 1. Center Frequency ( $F_0$ ) and Bandwidth (B) are defined, not measured. Dispersion (T) is defined as  $|B^*S_0|$ .
- 2. Insertion Loss is the minimum loss for  $|f-F_0| < .5B$
- 3. Delay and Slope determined by best fit quadratic pulse in  $|f F_0| < .5B$ .
- 4. Specifications are at 22 °C only. Unit will operate undamaged from -54 °C to 125 °C with shifts  $dF_0 = -x * F_0$ ,  $dT_0 = x * (T_0 + S_0 * F_0)$ ,  $dS_0 = x * 2 * S_0$ , where x = 3E-8 \* (temperature 22 °C)

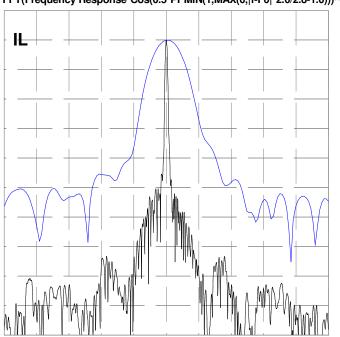
### **Typical Performance**

# Frequency Response (Best Fit Quadratic Phase Removed)



10 dB/div, 10 deg/div, 0.600 MHz/div

# Compressed Pulse Response FFT(Frequency Response\*Cos(0.5\*PI\*MIN(1,MAX(0,|f-F0|\*2.0/2.8-1.0)))^2)



10 dB/div, 10.000 us/div, 0.714 us/div



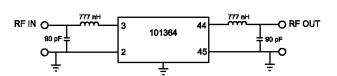
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### **Package Outline**

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## Matching





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